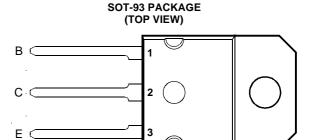
- Rugged Triple-Diffused Planar Construction
- 900 Volt Blocking Capability



Pin 2 is in electrical contact with the mounting base.

MDTRAA

# absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT		
Collector-base voltage (I <sub>E</sub> = 0)	BU426		800	V	
Collector-base voltage (I <sub>E</sub> = 0)	BU426A	V <sub>CBO</sub>	900	V	
Collector-emitter voltage (V <sub>RF</sub> = 0)	BU426	V	800	V	
Collector-entitles voltage (VBE = 0)	BU426A	V <sub>CES</sub>	900	V	
Collector-emitter voltage (I <sub>R</sub> = 0)	BU426	W	375	V	
Collector-entitler voltage (IB = 0)	BU426A	V <sub>CEO</sub>	400	V	
Continuous collector current	I <sub>C</sub>	6	Α		
Peak collector current (see Note 1)	I <sub>CM</sub>	10	Α		
Continuous base current	I <sub>B</sub>	+2, -0.1	Α		
Peak base current (see Note 1)	I <sub>BM</sub>	±3	Α		
Continuous device dissipation at (or below) 50°C case temperature	P <sub>tot</sub>	70	W		
Operating junction temperature range	Tj	-65 to +150	°C		
Storage temperature range	T <sub>stg</sub>	-65 to +150	°C		

NOTE 1: This value applies for  $t_p \le 2$  ms, duty cycle  $\le 2\%$ .



# BU426, BU426A NPN SILICON POWER TRANSISTORS

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# electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
Vasar	Collector-emitter	$I_{\rm C} = 100  \rm mA$	L = 25 mH	(see Note 2)	BU426	375			V
V <sub>CEO(sus)</sub>	sustaining voltage	10 - 100 111/1	L = 25 IIII I	(300 14010 2)	BU426A	400			•
		V <sub>CE</sub> = 800 V	$V_{BE} = 0$		BU426			1	
	Collector-emitter	V <sub>CE</sub> = 900 V	$V_{BE} = 0$		BU426A			1	mA
ICES	cut-off current	V <sub>CE</sub> = 800 V	$V_{BE} = 0$	$T_C = 125$ °C	BU426			2	
		V <sub>CE</sub> = 900 V	$V_{BE} = 0$	$T_C = 125$ °C	BU426A			2	
I	Emitter cut-off	V <sub>EB</sub> = 10 V	$I_C = 0$					10	mA
I <sub>EBO</sub>	current	1 AER - 10 A	10 - 0					10	1117 \
h <sub>FE</sub>	Forward current	V <sub>CF</sub> = 5 V	$I_{\rm C} = 0.6  {\rm A}$	(see Notes 3 and 4)		30	60		
"FE	transfer ratio	ACE - 2 A	IC = 0.0 A	C = 0.0 A (See Notes 3 and 4)			30		
V	Collector-emitter	$I_B = 0.5 A$	$I_C = 2.5 A$	(see Notes 3 and 4)				1.5	V
V <sub>CE(sat)</sub>	saturation voltage	I <sub>B</sub> = 1.25 A	$I_C = 4 A$					3	V
V	Base-emitter	I <sub>B</sub> = 0.5 A	$I_C = 2.5 A$	(see Notes 3 and 4)				1.4	V
V <sub>BE(sat)</sub>	saturation voltage	I <sub>B</sub> = 1.25 A	$I_C = 4 A$					1.6	V

NOTES: 2. Inductive loop switching measurement.

- 3. These parameters must be measured using pulse techniques,  $t_p$  = 300  $\mu$ s, duty cycle  $\leq$  2%.
- 4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

# thermal characteristics

	PARAMETER			MAX	UNIT
$R_{\theta J}$	C Junction to case thermal resistance			1.1	°C/W

# resistive-load-switching characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER TEST CONDITIONS †			MIN	TYP	MAX	UNIT	
t <sub>on</sub>	Turn on time	I <sub>C</sub> = 2.5 A	I <sub>B(on)</sub> = 0.5 A	I <sub>B(off)</sub> = -1 A		0.3	0.6	μs
t <sub>s</sub>	Storage time	$V_{CC} = 250 \text{ V}$	(see Figures 1 and 2)			2	3.5	μs
t <sub>f</sub>	Fall time					0.15		μs
t <sub>f</sub>	Fall time	$I_C = 2.5 \text{ A}$ $V_{CC} = 250 \text{ V}$	I <sub>B(on)</sub> = 0.5 A T <sub>C</sub> = 95°C	$I_{B(off)} = -1 A$		0.2	0.75	μs

 $<sup>\ ^{\</sup>dagger}\ \ \text{Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.}$ 

# PRODUCT INFORMATION

# PARAMETER MEASUREMENT INFORMATION

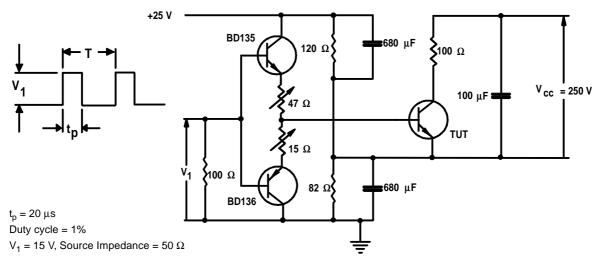


Figure 1. Resistive-Load Switching Test Circuit

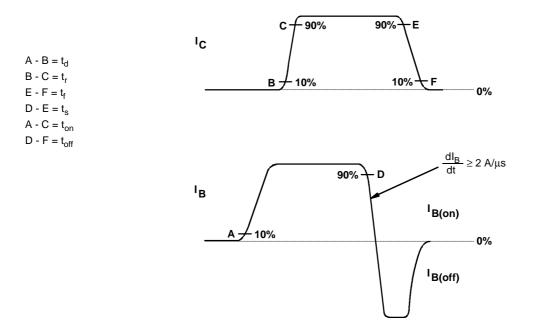


Figure 2. Resistive-Load Switching Waveforms

# TYPICAL CHARACTERISTICS

# TYPICAL DC CURRENT COLLECTOR CURRENT TCP741AF V<sub>CE</sub> = 1.5 V V<sub>CE</sub> = 5 V 1.0 1.0 1.0 I<sub>C</sub> - Collector Current - A

# **COLLECTOR-EMITTER SATURATION VOLTAGE**

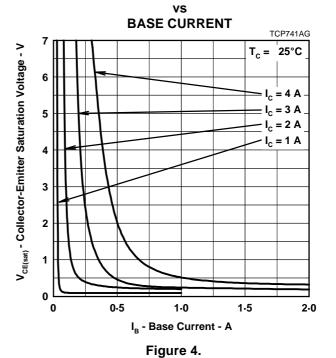
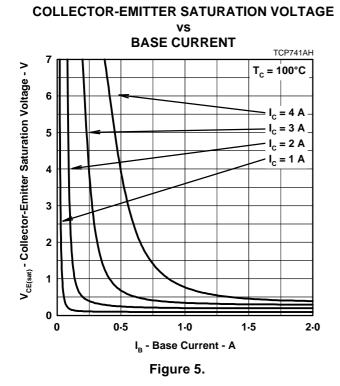
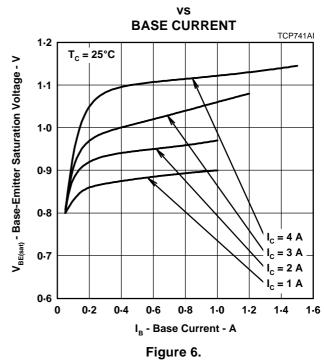


Figure 3.



# **BASE-EMITTER SATURATION VOLTAGE**



# PRODUCT INFORMATION

# **MAXIMUM SAFE OPERATING REGIONS**

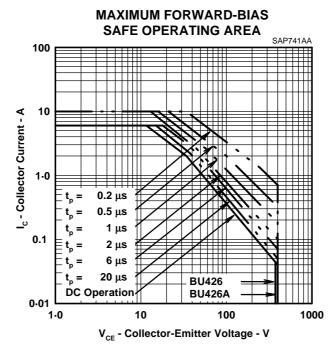


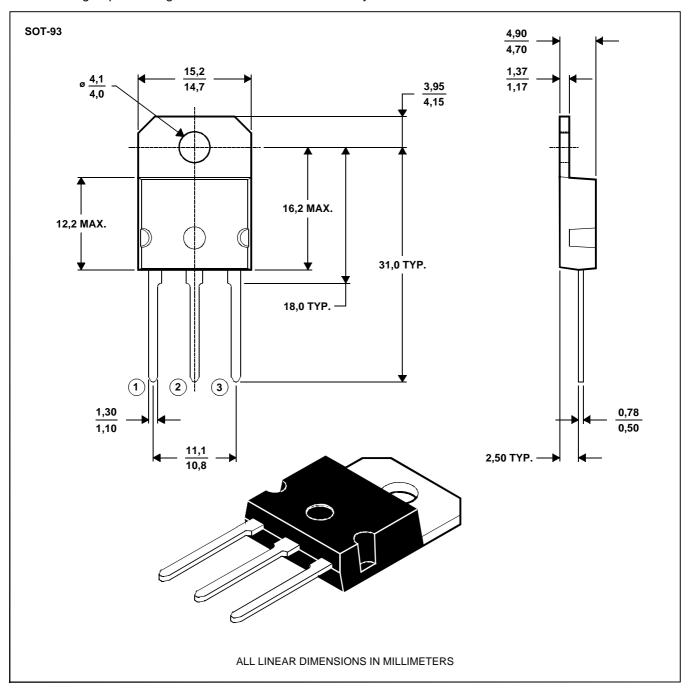
Figure 7.

## **MECHANICAL DATA**

# **SOT-93**

# 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

**MDXXAW** 

# PRODUCT INFORMATION

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